

Amendments to the Claims

This listing of the claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1. (currently amended) An on-chip test apparatus comprising:

a first and a second data latch fabricated on-chip, each of said first and second data latches having a respective input and a respective output;

a test structure fabricated on-chip; and

a selective coupling means for selectively coupling the output of the first data latch to the input of the second data latch either directly or through the test structure,

the selective coupling means including -

a first multiplexer having a pair of first mux inputs and a first mux output, and

a second multiplexer having a pair of second mux inputs and a second mux output,

one of said pair of first mux inputs coupled to the first data latch output, the first mux output coupled to an input of the test structure and one of said pair of second mux inputs, the other of said pair of second mux inputs coupled to an output of the test structure, the second mux output coupled to the second data latch input.

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2. (cancelled)

3. (Cancelled)

4. (cancelled)

5. (currently amended) The on-chip test apparatus as claimed in claim 3 1 wherein the other of said pair of first mux inputs is coupled to an inverted first data latch output.

6. (currently amended) The on-chip test apparatus as claimed in claim 3 1 wherein the other of said pair of first mux inputs is coupled to a predetermined test signal.

7. (original) The on-chip test apparatus as claimed in claim 6 wherein the predetermined test signal comprises an inverted first data latch output.

8. (original) An on-chip test apparatus comprising:

a first and a second data latch fabricated on-chip,
each of said first and second data latches having a

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respective input and a respective output;

a test structure fabricated on-chip;

a first multiplexer having a pair of first mux inputs and a first mux output;

a second multiplexer having a pair of second mux inputs and a second mux output; and

one of said pair of first mux inputs coupled to the first data latch output, the other of said pair of first mux inputs coupled to an inverted first data latch output, the first mux output coupled to an input of the test structure and one of said pair of second mux inputs, the other of said pair of second mux inputs coupled to an output of the test structure, the second mux output coupled to the second data latch input.

9. (original) A multi-stage on-chip test apparatus comprising:

a test stage comprising:

a data latch fabricated on-chip, said data latch having a data latch input and a data latch output;

a test structure fabricated on-chip, said test structure having a test input and a test output;

a first multiplexer having a pair of first mux

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inputs and a first mux output;

a second multiplexer having a pair of second mux inputs and a second mux output;

one of said pair of first mux inputs coupled to the data latch output and the other of said pair of first mux inputs coupled to an inverted data latch output, the first mux output coupled to the test input and to one of said pair of second mux inputs, the other of said pair of second mux inputs coupled to the test output.

10. (original) The on-chip test apparatus as claimed in claim 9 wherein a plurality of test stages are concatenated such that a subsequent test stage data latch input is coupled to a preceding test stage second mux output.

11. (currently amended) An on-chip test apparatus comprising:

an n-bit shift register fabricated on-chip, said shift register including n data latches;

n-1 test structures fabricated on-chip; and

selective coupling means associated with each pair

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of adjacent data latches for selectively coupling adjacent data latches either directly or via a respective test structure, wherein loading and unloading of test data occurs when the adjacent data latches are coupled directly and testing of the test structures occurs when the adjacent data latches are coupled through the test structures,

each of said selective coupling means including -

a first multiplexer having a pair of first mux inputs and a first mux output, and

a second multiplexer having a pair of second mux inputs and a second mux output,

wherein one of said pair of first mux inputs coupled to a first data latch output, the other of said pair of first mux inputs coupled to an inverted first data latch output, the first mux output coupled to an input of a respective one of the test structures and one of said pair of second mux inputs, the other of said pair of second mux inputs coupled to an output of the respective one of the test structures, the second mux output coupled to a second data latch input.

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12. (cancelled)

13. (cancelled)

14. (cancelled)

15. (cancelled)

16. (new) A method for conducting an on-chip test on an IC chip, comprising the steps of:

providing an IC chip;

fabricating a first and a second data latch on said IC chip, each of said first and second data latches having a respective input and a respective output;

fabricating a test structure on said IC chip;

providing a selective coupling means for selectively coupling the output of the first data latch to the input of the second data latch either directly or through the test structure,

the selective coupling means including a first multiplexer having a pair of first mux inputs and a first mux output, and a second multiplexer having a pair of second mux inputs and a second mux output;

coupling one of said pair of first mux inputs to

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the first data latch output;

coupling the first mux output coupled to an input of the test structure and one of said pair of second mux inputs;

coupling the other of said pair of second mux inputs to an output of the test structure; and,

coupling the second mux output to the second data latch input.